

STx45N65M5

N-channel 650 V, 0.067 Ω 35 A MDmesh™ V Power MOSFET in D²PAK, TO-220FP, TO-220 and TO-247 packages

Features

Order code	V _{DSS} @ T _{Jmax}	R _{DS(on)} max	I _D
STB45N65M5			
STF45N65M5	710 V	< 0.078 Ω	35 A
STP45N65M5	710 V	< 0.076 \$2	33 A
STW45N65M5			

- Worldwide best R_{DS(on)} * area
- Higher V_{DSS} rating and high dv/dt capability
- Excellent switching performance
- 100% avalanche tested

Applications

■ Switching applications

Description

These devices are N-channel MDmesh™ V Power MOSFETs based on an innovative proprietary vertical process technology, which is combined with STMicroelectronics' well-known PowerMESH™ horizontal layout structure. The resulting product has extremely low onresistance, which is unmatched among siliconbased Power MOSFETs, making it especially suitable for applications which require superior power density and outstanding efficiency.

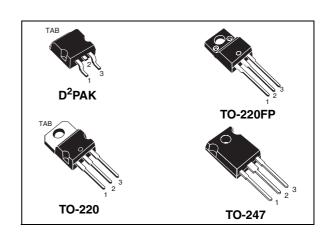


Figure 1. Internal schematic diagram

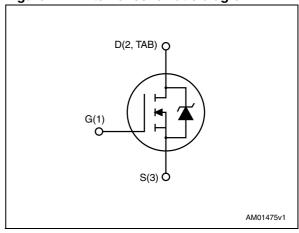


Table 1. Device summary

Order code	Marking	Package	Packaging
STB45N65M5		D ² PAK	Tape and reel
STF45N65M5	45N65M5	TO-220FP	
STP45N65M5	4511051015	TO-220	Tube
STW45N65M5		TO-247	

February 2012 Doc ID 022854 Rev 1 1/17

Contents STx45N65M5

Contents

1	Electrical ratings
2	Electrical characteristics
3	Test circuits6
4	Package mechanical data
5	Packaging mechanical data14
6	Revision history

STx45N65M5 Electrical ratings

1 Electrical ratings

Table 2. Absolute maximum ratings

		Va	lue	
Symbol	Parameter	D ² PAK TO-220 TO-247	TO-220FP	Unit
V _{GS}	Gate-source voltage	±	25	V
I _D	Drain current (continuous) at T _C = 25 °C	35	35 ⁽¹⁾	Α
I _D	Drain current (continuous) at T _C = 100 °C	22	22 ⁽¹⁾	Α
I _{DM} ⁽¹⁾	Drain current (pulsed)	140	140 ⁽¹⁾	Α
P _{TOT}	Total dissipation at T _C = 25 °C	208	40	W
dv/dt (2)	Peak diode recovery voltage slope	1	5	V/ns
V _{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s; Tc = 25 °C)	2500		V
T _{stg}	Storage temperature	- 55 to 150		°C
T _j	Max. operating junction temperature	15	50	°C

^{1.} Limited by maximum junction temperature.

Table 3. Thermal data

Symbol Parameter		Value					
Symbol	Farameter	D ² PAK	D ² PAK TO-220FP TO-220 TO-24		TO-247	- Unit	
R _{thj-case}	Thermal resistance junction- case max	0.60	3.13	0.60		°C/W	
R _{thj-pcb} ⁽¹⁾	Thermal resistance junction- pcb max	30				°C/W	
R _{thj-amb}	Thermal resistance junction- ambient max		62.5 50		50	°C/W	

^{1.} When mounted on 1 inch² FR-4, 2 Oz copper board.

Table 4. Avalanche characteristics

Symbol	Parameter	Value	Unit
I _{AR}	Avalanche current, repetetive or not repetetive (pulse width limited by T_{jmax})	TBD	А
E _{AS}	Single pulse avalanche energy (starting t_j =25°C, I_d = I_{AR} ; V_{dd} =50)	TBD	mJ

^{2.} $I_{SD} \leq 35 \text{ A, di/dt } \leq 400 \text{ A/µs; } V_{DD} < 80 \% V_{(BR)DSS}$

Electrical characteristics STx45N65M5

2 Electrical characteristics

(T_C = 25 °C unless otherwise specified)

Table 5. On /off states

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	I _D = 1 mA, V _{GS} = 0	650			V
I _{DSS}	Zero gate voltage drain current (V _{GS} = 0)	V _{DS} = 650 V V _{DS} = 650 V, T _C =125 °C			1 100	μ Α μ Α
I _{GSS}	Gate-body leakage current (V _{DS} = 0)	V _{GS} = ± 25 V			± 100	nA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3	4	5	٧
R _{DS(on)}	Static drain-source on-resistance	V _{GS} = 10 V, I _D = 19.5 A		0.067	0.078	Ω

Table 6. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{iss} C _{oss} C _{rss}	Input capacitance Output capacitance Reverse transfer capacitance	$V_{DS} = 100 \text{ V, f} = 1 \text{ MHz,}$ $V_{GS} = 0$	-	3375 92 10	-	pF pF pF
C _{o(tr)} ⁽¹⁾	Equivalent capacitance time related	V _{DS} = 0 to 520 V, V _{GS} = 0	-	TBD	-	pF
C _{o(er)} ⁽²⁾	Equivalent capacitance energy related	V _{DS} = 0 to 320 v, v _{GS} = 0	-	TBD	-	pF
R _G	Intrinsic gate resistance	f = 1 MHz open drain	-	1.6	-	Ω
Qg	Total gate charge	V _{DD} = 520 V, I _D = 19.5 A,		91		nC
Q_{gs}	Gate-source charge	V _{GS} = 10 V	-	21	-	nC
Q_{gd}	Gate-drain charge	(see Figure 3)		38		nC

^{1.} Time related is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}

^{2.} Energy related is defined as a constant equivalent capacitance giving the same stored energy as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}

Table 7. Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max	Unit
$\begin{array}{c} t_{d} \ (v) \\ t_{r} \ (v) \\ t_{f} \ (i) \\ t_{c} (off) \end{array}$	Voltage delay time Voltage rise time Current fall time Crossing time	V_{DD} = 400 V, I_{D} = 21 A, R_{G} = 4.7 Ω , V_{GS} = 10 V (see <i>Figure 4</i> and <i>Figure 7</i>)	-	TBD TBD TBD TBD	-	ns ns ns ns

Table 8. Source drain diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain current Source-drain current (pulsed)		-		35 140	A A
V _{SD} ⁽²⁾	Forward on voltage	I _{SD} = 35 A, V _{GS} = 0	-		1.5	V
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I _{SD} = 35 A, di/dt = 100 A/μs V _{DD} = 100 V (see <i>Figure 7</i>)	1	TBD TBD TBD		ns μC A
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 35 \text{ A, di/dt} = 100 \text{ A/µs}$ $V_{DD} = 100 \text{ V, T}_j = 150 ^{\circ}\text{C}$ (see <i>Figure 7</i>)	1	TBD TBD TBD		ns μC A

^{1.} Pulse width limited by safe operating area.

^{2.} Pulsed: pulse duration = $300 \mu s$, duty cycle 1.5%

Test circuits STx45N65M5

3 Test circuits

Figure 2. Switching times test circuit for resistive load

Figure 3. Gate charge test circuit

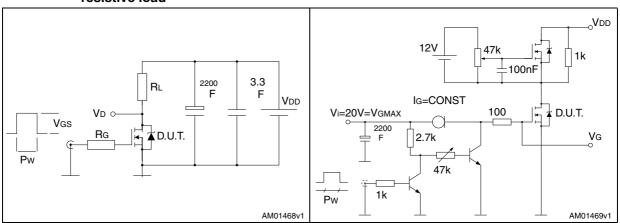


Figure 4. Test circuit for inductive load switching and diode recovery times

Figure 5. Unclamped inductive load test circuit

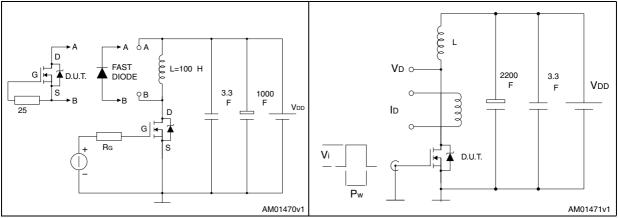
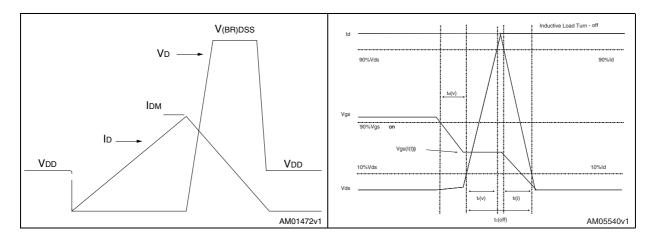


Figure 6. Unclamped inductive waveform

Figure 7. Switching time waveform



577

4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Table 9. D²PAK (TO-263) mechanical data

Dim		mm	
Dim.	Min.	Тур.	Max.
А	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
С	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50		
Е	10		10.40
E1	8.50		
е		2.54	
e1	4.88		5.28
Н	15		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.4	
V2	0°		8°

0079457_T

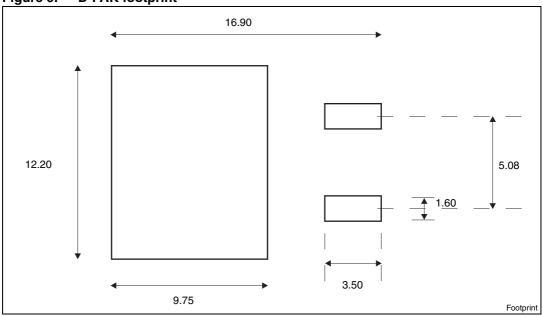
THERMAL PAD

SEATING PLANE

COPLANARITY A1

Figure 8. D²PAK (TO-263) drawing





0.25

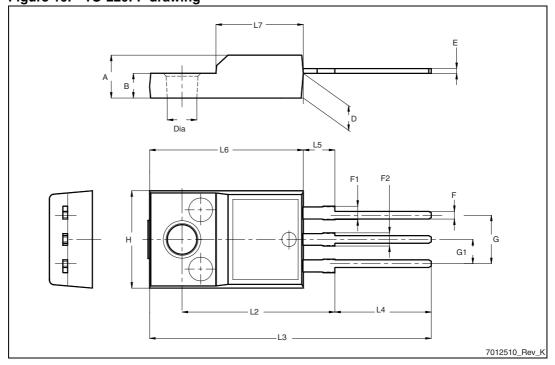
GAUGE PLANE

a. All dimension are in millimeters

Table 10. TO-220FP mechanical data

Di	mm				
Dim.	Min.	Тур.	Max.		
А	4.4		4.6		
В	2.5		2.7		
D	2.5		2.75		
Е	0.45		0.7		
F	0.75		1		
F1	1.15		1.70		
F2	1.15		1.70		
G	4.95		5.2		
G1	2.4		2.7		
Н	10		10.4		
L2		16			
L3	28.6		30.6		
L4	9.8		10.6		
L5	2.9		3.6		
L6	15.9		16.4		
L7	9		9.3		
Dia	3		3.2		

Figure 10. TO-220FP drawing



477

Table 11. TO-220 type A mechanical data

Dim.	mm			
	Min.	Тур.	Max.	
Α	4.40		4.60	
b	0.61		0.88	
b1	1.14		1.70	
С	0.48		0.70	
D	15.25		15.75	
D1		1.27		
Е	10		10.40	
е	2.40		2.70	
e1	4.95		5.15	
F	1.23		1.32	
H1	6.20		6.60	
J1	2.40		2.72	
L	13		14	
L1	3.50		3.93	
L20		16.40		
L30		28.90		
ØP	3.75		3.85	
Q	2.65		2.95	

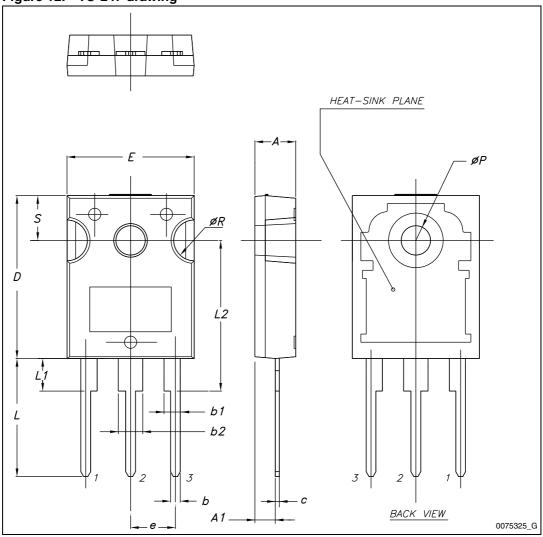
D D1 L30 D1 L30

Figure 11. TO-220 type A drawing

Table 12. TO-247 mechanical data

Dim	mm.				
Dim.	Min.	Тур.	Max.		
А	4.85		5.15		
A1	2.20		2.60		
b	1.0		1.40		
b1	2.0		2.40		
b2	3.0		3.40		
С	0.40		0.80		
D	19.85		20.15		
E	15.45		15.75		
е	5.30	5.45	5.60		
L	14.20		14.80		
L1	3.70		4.30		
L2		18.50			
ØP	3.55		3.65		
ØR	4.50		5.50		
S	5.30	5.50	5.70		

Figure 12. TO-247 drawing



5 Packaging mechanical data

Table 13. D²PAK (TO-263) tape and reel mechanical data

14515 1	Таре	oo, tapo ana roor i	Reel		
Dim.	mm		Dim	mm	
	Min.	Max.	Dim.	Min.	Max.
A0	10.5	10.7	Α		330
В0	15.7	15.9	В	1.5	
D	1.5	1.6	С	12.8	13.2
D1	1.59	1.61	D	20.2	
Е	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	Т		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base qty 1000		1000
P2	1.9	2.1		Bulk qty	1000
R	50				
Т	0.25	0.35			
W	23.7	24.3			

14/17 Doc ID 022854 Rev 1

Figure 13. Tape

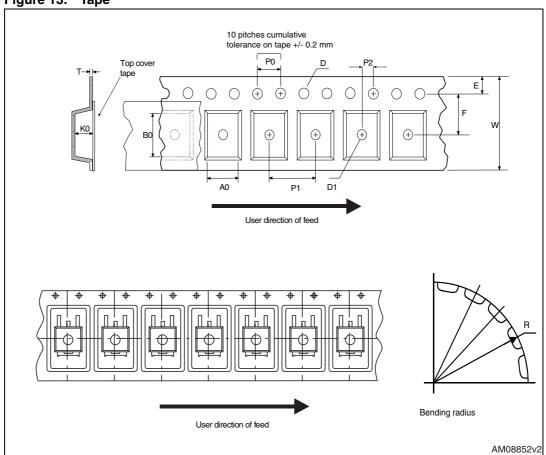
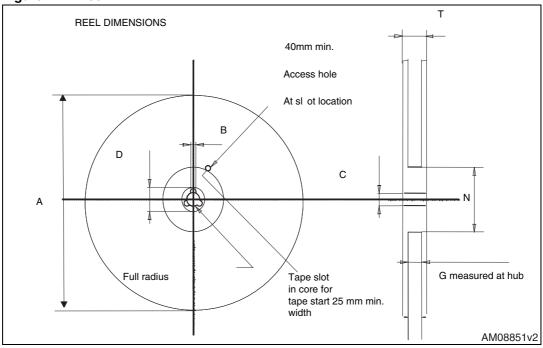


Figure 14. Reel



Revision history STx45N65M5

6 Revision history

Table 14. Document revision history

Date	Revision	Changes
22-Feb-2012	1	First release.

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY TWO AUTHORIZED ST REPRESENTATIVES, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2012 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com

